

### 3.3V ZERO DELAY CLOCK BUFFER

### FEATURES:

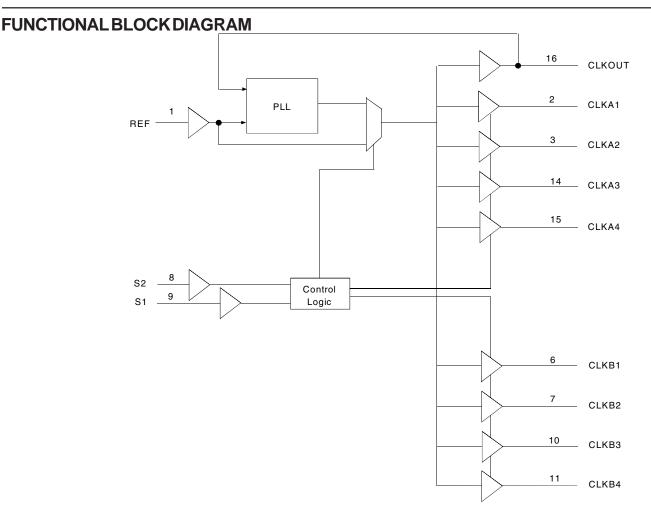
- Phase-Lock Loop Clock Distribution
- 10MHz to 133MHz operating frequency
- Distributes one clock input to one bank of five and one bankd of four outputs
- · Separate output enable for each output bank
- Output Skew < 250ps
- Low jitter <200 ps cycle-to-cycle
- IDT2309-1 for Standard Drive
- IDT2309-1H for High Drive
- · No external RC network required
- Operates at 3.3V VDD
- · Available in SOIC and TSSOP packages

### **DESCRIPTION:**

The IDT2309 is a high-speed phase-lock loop (PLL) clock buffer, designed to address high-speed clock distribution applications. The zero delay is achieved by aligning the phase between the incoming clock and the output clock, operable within the range of 10 to 133MHz.

The IDT2309 is a 16-pin version of the IDT2305. The IDT2309 accepts one reference input, and drives two banks of four low skew clocks. The -1H version of this device operates at up to 133MHz frequency and has higher drive than the -1 device. All parts have on-chip PLLs which lock to an input clock on the REF pin. The PLL feedback is on-chip and is obtained from the CLKOUT pad. In the absence of an input clock, the IDT2309 enters power down, and the outputs are tri-stated. In this mode, the device will draw less than  $25\mu$ A.

The IDT2309 is characterized for both Industrial and Commercial operation.



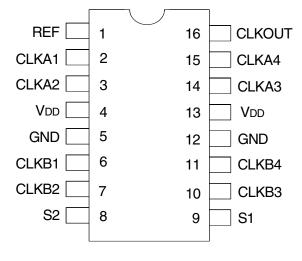
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### COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES

### **AUGUST 2012**

### COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES

### **PINCONFIGURATION**



SOIC/ TSSOP **TOP VIEW** 

### **APPLICATIONS:**

- SDRAM
- Telecom .
- Datacom
- PC Motherboards/Workstations
- Critical Path Delay Designs •

### **PIN DESCRIPTION**

# NOTES: clamp-current ratings are observed. of 150°C and a board trace length of 750 mils.

Pin Name	Pin Number	Туре	Functional Description
REF	1	IN	Input reference clock, 5 Volt tolerant input
CLKA1 <sup>(1)</sup>	2	Out	Output clock for bank A
CLKA2 <sup>(1)</sup>	3	Out	Output clock for bank A
Vdd	4, 13	PWR	3.3V Supply
GND	5, 12	GND	Ground
CLKB1 <sup>(1)</sup>	6	Out	Output clock for bank B
CLKB2 <sup>(1)</sup>	7	Out	Output clock for bank B
S2 <sup>(2)</sup>	8	IN	Select input Bit 2
S1 <sup>(2)</sup>	9	IN	Select input Bit 1
CLKB3 <sup>(1)</sup>	10	Out	Output clock for bank B
CLKB4 <sup>(1)</sup>	11	Out	Output clock for bank B
CLKA3 <sup>(1)</sup>	14	Out	Output clock for bank A
CLKA4 <sup>(1)</sup>	15	Out	Output clock for bank A
CLKOUT <sup>(1)</sup>	16	Out	Output clock, internal feedback on this pin

#### NOTES:

1. Weak pull down on all outputs.

2. Weak pull ups on these inputs.

### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Rating	Max.	Unit
Vdd	Supply Voltage Range	-0.5 to +4.6	V
VI <sup>(2)</sup>	Input Voltage Range (REF)	-0.5 to +5.5	V
VI	Input Voltage Range	–0.5 to	V
	(except REF)	VDD+0.5	
IIK (VI < 0)	Input Clamp Current	-50	mA
Io (Vo = 0 to VDD)	Continuous Output Current	±50	mA
VDD or GND	Continuous Current	±100	mA
$TA = 55^{\circ}C$	Maximum Power Dissipation	0.7	W
(in still air) <sup>(3)</sup>			
Tstg	Storage Temperature Range	-65 to +150	°C
Operating	CommercialTemperature	0 to +70	°C
Temperature	Range		
Operating	Industrial Temperature	-40 to +85	°C
Temperature	Range		

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. The input and output negative-voltage ratings may be exceeded if the input and output

3. The maximum package power dissipation is calculated using a junction temperature

### FUNCTION TABLE<sup>(1)</sup>

S2	S1	CLKA	CLKB	CLKOUT <sup>(2)</sup>	Output Source	PLL Shut Down
L	L	Tri-State	Tri-State	Driven	PLL	Ν
L	Н	Driven	Tri-State	Driven	PLL	N
Н	L	Driven	Driven	Driven	REF	Y
Н	Н	Driven	Driven	Driven	PLL	Ν

NOTES:

1. H = HIGH Voltage Level.

L = LOW Voltage Level

2. This output is driven and has an internal feedback for the PLL. The load on this ouput can be adjusted to change the skew between the REF and the output.

### DCELECTRICAL CHARACTERISTICS-COMMERCIAL

Symbol	Parameter	Condi	tions	Min.	Max.	Unit
Vil	Input LOW Voltage Level			—	0.8	V
Vih	Input HIGH Voltage Level			2	—	V
lil	Input LOW Current	VIN = 0V		—	50	μA
Ін	Input HIGH Current	VIN = VDD	VIN = VDD		100	μA
Vol	OutputLOWVoltage	Standard Drive	Iol = 8mA	—	0.4	V
		High Drive	IoL = 12mA (-1H)			
Vон	Output HIGH Voltage	Standard Drive	Iон = -8mA	2.4	_	V
		High Drive	Іон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz (S2 = S1 = H)		_	12	μA
Idd	Supply Current	Unloaded Outputs at 66.66M	Hz, SEL inputs at VDD or GND	-	32	mA

### **OPERATING CONDITIONS-COMMERCIAL**

Symbol	Parameter	Min.	Max.	Unit
Vdd	Supply Voltage	3	3.6	V
TA	Operating Temperature (Ambient Temperature)	0	70	°C
CL	Load Capacitance < 100MHz	—	30	pF
	Load Capacitance 100MHz - 133MHz	_	10	
Cin	Input Capacitance	_	7	pF

### SWITCHING CHARACTERISTICS (2309-1) - COMMERCIAL

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pF Load	10	—	133	MHz
		30pF Load	10	_	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
t3	RiseTime	Measured between 0.8V and 2V	—	—	2.5	ns
t4	FallTime	Measured between 0.8V and 2V	_	—	2.5	ns
ts	Output to Output Skew	All outputs equally loaded	_	—	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge <sup>(2)</sup>	Measured at VDD/2	—	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge <sup>(2)</sup>	Measured at VDD/2 in PLL bypass mode (IDT2309 only)	1	5	8.7	ns
t	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	—	0	700	ps
tı	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	—	200	ps
<b>t</b> LOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

### SWITCHING CHARACTERISTICS (2309-1H) - COMMERCIAL

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	—	133	MHz
		30pF Load	10	—	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT <50MHz	45	50	55	%
ß	RiseTime	Measured between 0.8V and 2V	_	_	1.5	ns
t4	FallTime	Measured between 0.8V and 2V	_	_	1.5	ns
ts	Output to Output Skew	All outputs equally loaded	_	_	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2 in PLL bypass mode (IDT2309 only)	1	5	8.7	ns
đ	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
<b>t</b> 8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit 2	1	_	_	V/ns
tı	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	_	200	ps
<b>t</b> LOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	—	1	ms

NOTES:

REF Input has a threshold voltage of VDD/2.
All parameters specified with loaded outputs.

### DC ELECTRICAL CHARACTERISTICS-INDUSTRIAL

Symbol	Parameter	Conditi	ons	Min.	Max.	Unit
Vil	Input LOW Voltage Level			—	0.8	V
Vih	Input HIGH Voltage Level			2	—	V
lil	Input LOW Current	VIN = 0V		—	50	μA
Ін	Input HIGH Current	VIN = VDD		—	100	μA
Vol	Output LOW Voltage	Standard Drive	Iol = 8mA	—	0.4	V
		High Drive	IoL = 12mA (-1H)			
Vон	Output HIGH Voltage	Standard Drive	IOH = -8mA	2.4	—	V
		High Drive	Іон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz (S2 = S1 = H)		—	25	μA
IDD	Supply Current	Unloaded Outputs at 66.66MH	z, SEL inputs at VDD or GND	—	35	mA

### **OPERATING CONDITIONS-INDUSTRIAL**

Symbol	Parameter	Min.	Max.	Unit
Vdd	SupplyVoltage	3	3.6	V
TA	Operating Temperature (Ambient Temperature)	-40	+85	°C
CL	Load Capacitance < 100MHz	—	30	pF
	Load Capacitance 100MHz - 133MHz	_	10	
Cin	InputCapacitance	_	7	pF

## SWITCHING CHARACTERISTICS (2309-1) - INDUSTRIAL (1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pF Load	10	_	133	MHz
		30pF Load	10	_	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
t3	RiseTime	Measured between 0.8V and 2V	_	_	2.5	ns
t4	FallTime	Measured between 0.8V and 2V	—	_	2.5	ns
ts	Output to Output Skew	All outputs equally loaded	_	_	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2 in PLL bypass mode (IDT2309 only)	1	5	8.7	ns
t	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
tı	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	_	200	ps
tlock	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

#### NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

### SWITCHING CHARACTERISTICS (2309-1H) - INDUSTRIAL (1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	_	133	MHz
		30pF Load	10	—	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT <50MHz	45	50	55	%
t3	RiseTime	Measured between 0.8V and 2V	_	_	1.5	ns
t4	FallTime	Measured between 0.8V and 2V	_	_	1.5	ns
ts	Output to Output Skew	All outputs equally loaded	_	_	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2 in PLL bypass mode (IDT2309 only)	1	5	8.7	ns
đ	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
t8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit 2	1	_	-	V/ns
tı	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	_	200	ps
tlock	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

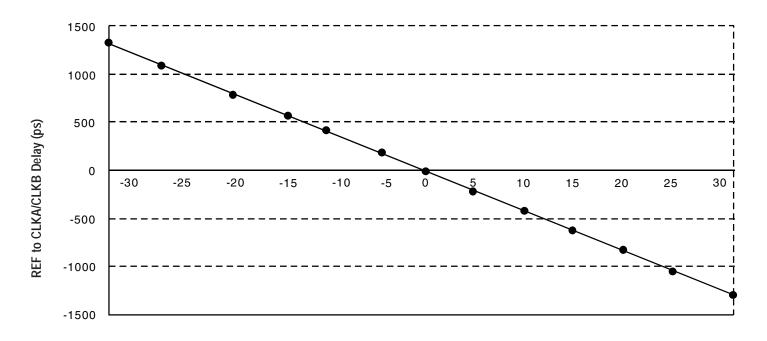
1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

### **ZERO DELAY AND SKEW CONTROL**

All outputs should be uniformly loaded in order to achieve Zero I/O Delay. Since the CLKOUT pin is the internal feedback for the PLL, its relative loading can affect and adjust the input/output delay. The Output Load Difference diagram illustrates the PLL's relative loading with respect to the other outputs that can adjust the Input-Output (I/O) Delay.

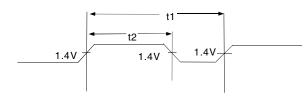
For designs utilizing zero I/O Delay, all outputs including CLKOUT must be equally loaded. Even if the output is not used, it must have a capacitive load equal to that on the other outputs in order to obtain true zero I/O Delay. If I/O Delay adjustments are needed, use the Output Load Difference diagram to calculate loading differences between the CLKOUT pin and other outputs. For zero output-to-output skew, all outputs must be loaded equally.



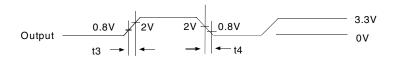
REF TO CLKA/CLKB RELAY vs. OUTPUT LOAD DIFFERENCE BETWEEN CLKOUT PIN AND CLKA/CLKB PINS

### OUTPUT LOAD DIFFERENCE BETWEEN CLKOUT PIN AND CLKA/CLKB PINS (pF)

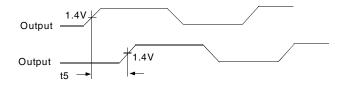
### SWITCHING WAVEFORMS



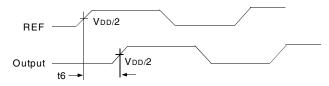
Duty Cycle Timing



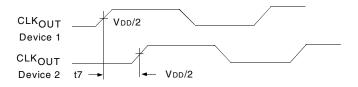
All Outputs Rise/Fall Time



Output to Output Skew

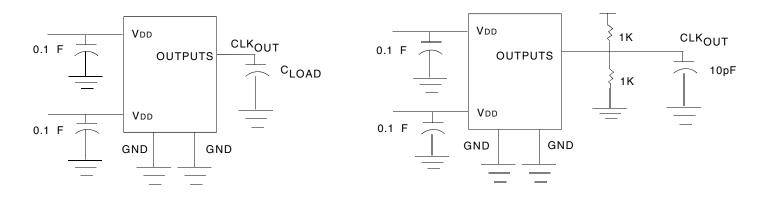


Input to Output Propagation Delay





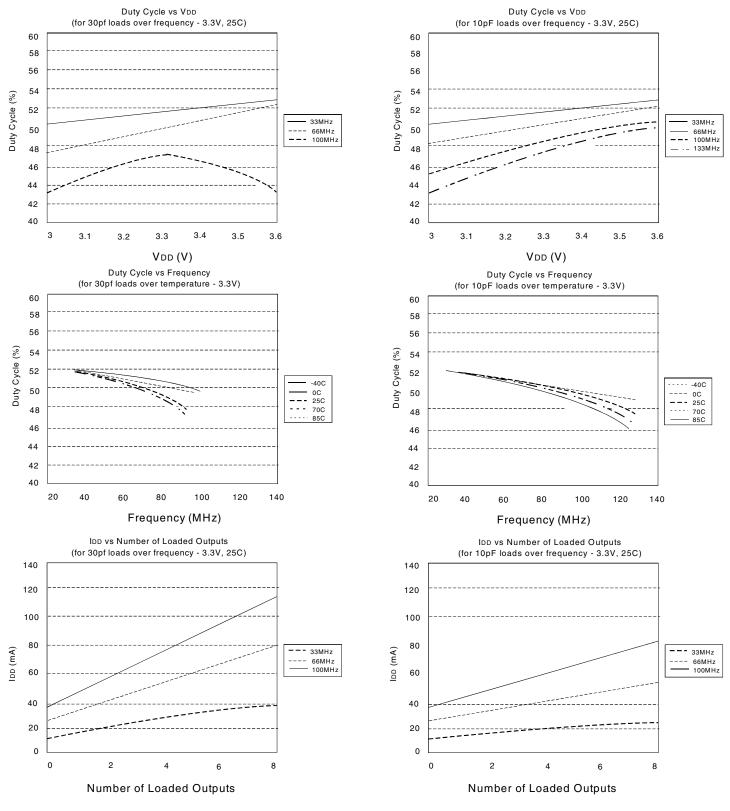
### **TEST CIRCUITS**



Test Circuit 1 (all Parameters Except t8)



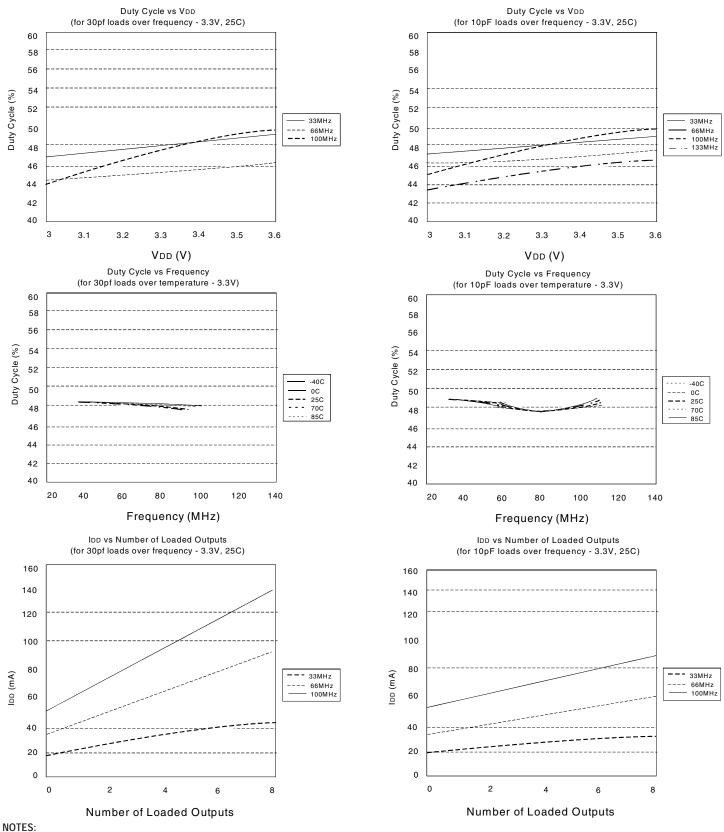
### TYPICAL DUTY CYCLE<sup>(1)</sup> AND IDD TRENDS<sup>(2)</sup> FOR IDT2309-1



#### NOTES:

- 1. Duty Cycle is taken from typical chip measured at 1.4V.
- 2. Ibb data is calculated from Ibb = IcoRE + nCVf, where IcoRE is the unloaded current. (n = Number of outputs; C = Capacitance load per output (F); V = Supply Voltage (V); f = Frequency (Hz))

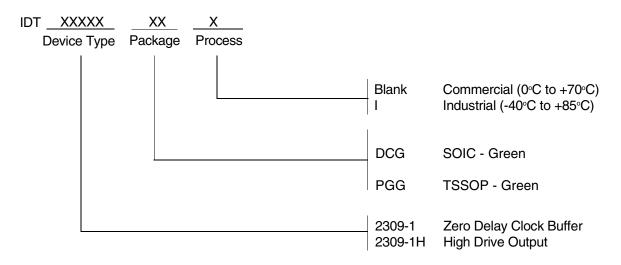
### TYPICAL DUTY CYCLE<sup>(1)</sup> AND IDD TRENDS<sup>(2)</sup> FOR IDT2309-1H



1. Duty Cycle is taken from typical chip measured at 1.4V.

2. IDD data is calculated from IDD = ICORE + nCVf, where ICORE is the unloaded current. (n = Number of outputs; C = Capacitance load per output (F); V = Supply Voltage (V); f = Frequency (Hz))

### **ORDERING INFORMATION**



Ordering Code	Package Type	Operating Range
IDT2309-1DCG	16-Pin SOIC	Commercial
IDT2309-1DCGI	16-Pin SOIC	Industrial
IDT2309-1HDCG	16-Pin SOIC	Commercial
IDT2309-1HDCGI	16-Pin SOIC	Industrial
IDT2309-1HPG	16-Pin TSSOP	Commercial
IDT2309-1HPGG	16-Pin TSSOP	Commercial
IDT2309-1HPGI	16-Pin TSSOP	Industrial
IDT2309-1HPGGI	16-Pin TSSOP	Industrial

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(Rev.1.0 Mar 2020)

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